

# 标准&定制开关连接器产品制造商 DONG GUAN XI BANG ELECTRONICS CO., LTD.

# 16 PIN ULTRA SMALL SSOP AC INPUT PHOTOTRANSISTOR PHOTOCOUPLER ELQ3H4 Series





#### **Features**

- · Halogens free
- AC input response
- Current transfer ratio (CTR: 20~300% at IF =1mA, VCE =5V)
- High isolation voltage between input and output (Viso=3750 V rms)
- Compact SSOP with a 2.0 mm profile
- Pb free and RoHS compliant.
- UL approved (No. E214129)
- VDE approved (No. 40028116)
- SEMKO approved
- NEMKO approved
- · DEMKO approved
- FIMKO approved
- CQC approved

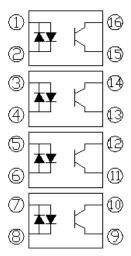
# **Description**

The ELQ3H4 is optically coupled isolator containing GaAs light emitting diodes and an NPN silicon phototransistors in a plastic SOP for high density applications. This package has shield effect to cut off ambient light.

# **Applications**

- Programmable logic controllers
- Measuring instruments
- Hybrid IC





①357 Anode/Cathode

2468 Cathode/Anode

⑨⑪⑬⑮ Emitter

0 12 19 19 Collector

# Absolute Maximum Ratings (T<sub>A</sub>=25°C)

	Parameter	Symbol	Rating	Unit
	Forward current	I <sub>F</sub>	±60	mA
	Peak forward current (1us, pulse)	I <sub>FP</sub>	1	А
Input	Power dissipation	D	70	mW/Ch
	Power Dissipation Derating	P <sub>D</sub> —	0.7	mW/°C
	Collector current	I <sub>C</sub>	50	mA
	Collector-Emitter voltage	V <sub>CEO</sub>	80	V
Output	Emitter-Collector voltage	V <sub>ECO</sub>	7	V
	Power dissipation	D	150	mW /Ch
	Power Dissipation Derating	P <sub>C</sub> —	1.4	mW/°C
Total power dissipation		P <sub>TOT</sub>	200	mW
Isolation voltage *1		V <sub>ISO</sub>	3750	V rms
Operating temperature		T <sub>OPR</sub>	-55 ~ +110	°C
Storage temperature		T <sub>STG</sub>	-55 ~ +125	°C
Soldering temperature *2		T <sub>SOL</sub>	260	°C

#### Notes:

 $<sup>^{*}1</sup>$  AC for 1 minute, R.H.=  $40 \sim 60\%$  R.H. In this test, LED side pins shorted together, and detector side pins shorted together.

<sup>\*2</sup> For 10 seconds

# Electrical Characteristics (T<sub>A</sub>=25°C unless specified otherwise)

Input

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward voltage	$V_{F}$	-	1.2	1.4	V	I <sub>F</sub> =± 20mA
Input Capacitance	$C_in$	-	30	250	pF	V = 0, f = 1KHz

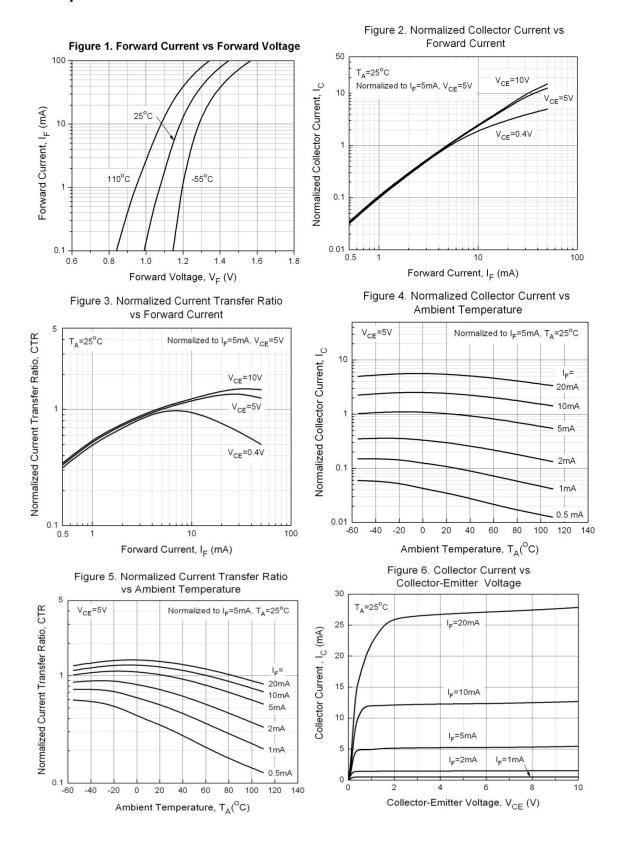
Output

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Collector-Emitter dark current	I <sub>CEO</sub>	-	-	100	nA	$V_{CE} = 20V$ , $I_F = 0mA$
Collector-Emitter breakdown voltage	$BV_CEO$	80	-	-	V	I <sub>C</sub> = 0.1mA
Emitter-Collector breakdown voltage	BV <sub>ECO</sub>	7	-	-	V	I <sub>E</sub> = 0.1mA

Transfer Characteristics (T<sub>A</sub>=-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min	Тур.	Max.	Unit	Condition
Current Transfer ratio	CTR	20	-	300	%	$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$
CTR Ratio	CTR1/ CTR2	0.5	-	2.0		$I_F = \pm 1 \text{mA}, V_{CE} = 5 \text{V}$
Collector-Emitter saturation voltage	V <sub>CE(sat)</sub>	-	0.1	0.2	V	$I_F = \pm 20 \text{mA}$ , $I_C = 1 \text{mA}$
Isolation resistance	R <sub>IO</sub>	5×10 <sup>10</sup>	-	-	Ω	V <sub>IO</sub> = 500Vdc, 40~60% R.H.
Floating capacitance	C <sub>IO</sub>	-	0.3	1.0	pF	V <sub>IO</sub> = 0, f = 1MHz
Rise time	t <sub>r</sub>	-	5	18	μs	$V_{CE} = 2V$ , $I_C = 2mA$ ,
Fall time	t <sub>f</sub>	-	3	18	μs	$R_L = 100\Omega$

# **Typical Electro-Optical Characteristics Curves**



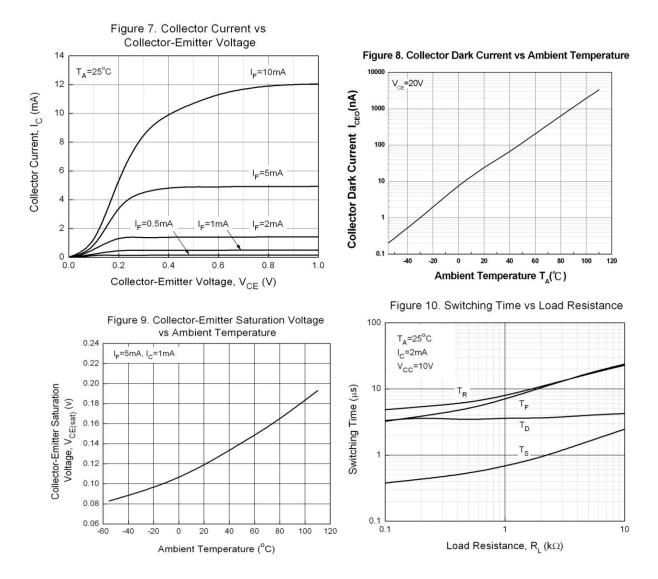
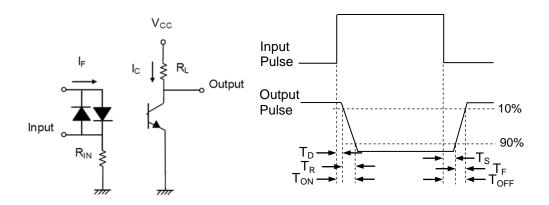


Figure 11. Switching Time Test Circuit & Waveform



# **Order Information**

# **Part Number**

# ELQ3H4(Z)-V

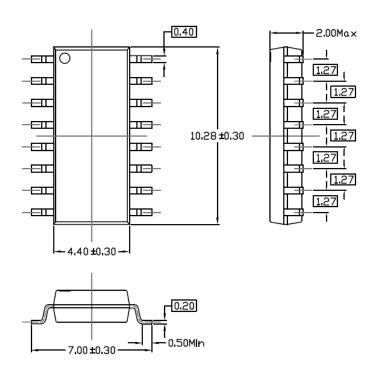
#### Note

= Tape and reel option (TA or none). = VDE (optional) Z V

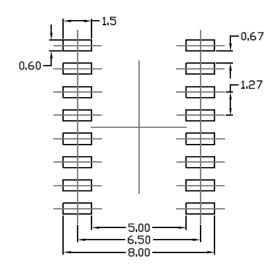
Option	Description	Packing quantity	
None	Tube option of ELQ3H4	40 units per tube	
(TA)	Tape & reel option of ELQ3H4	1000 units per reel	

# **Package Dimension**

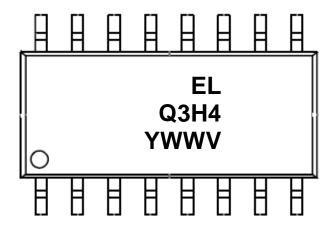
# (Dimensions in mm)



# Recommended pad layout for surface mount leadform



# **Device Marking**



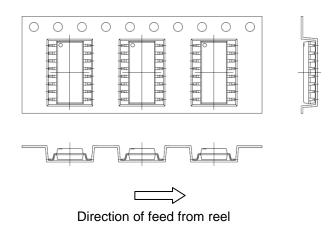
#### **Notes**

EL denotes XI BNANG Q3H4 denotes Device Number Y denotes 1 digit Year code WW denotes 2 digit Week code V denotes VDE (optional)

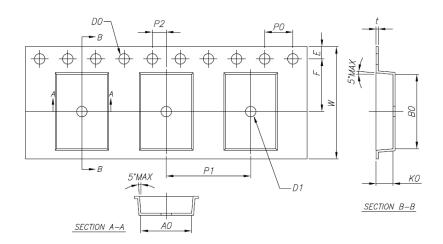


**Tape & Reel Packing Specifications** 

# ELQ3H4



# **Tape dimension**

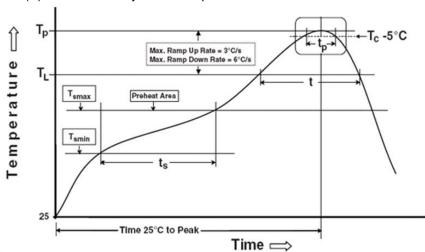


Dimension No.	A0	В0	D0	D1	E	F
Dimension (mm)	7.2±0.1	10.6±0.1	1.5+0.1 -0	1.5+0.1 -0	1.75±0.1	7.5±0.1
Dimension No.	P0	P1	P2	t	W	КО
Dimension (mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.3±0.05	16.0±0.3	2.4±0.1

# **Precautions for Use**

# 1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note: Reference: IPC/JEDEC J-STD-020D

#### **Preheat**

Temperature min (T <sub>smin</sub> )	150 °C
Temperature max (T <sub>smax</sub> )	200°C
Time $(T_{smin} \text{ to } T_{smax})$ $(t_s)$	60-120 seconds
Average ramp-up rate (T <sub>smax</sub> to T <sub>p</sub> )	3 °C/second max

# Other

Liquidus Temperature (T <sub>L</sub> )	217 °C
Time above Liquidus Temperature (t L)	60-100 sec
Peak Temperature (T <sub>P</sub> )	260°C
Time within 5 °C of Actual Peak Temperature: T <sub>P</sub> - 5°C	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature Reflow times	8 minutes max. 3 times

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